



ABSTRACT

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A substrate processing apparatus comprises a substrate processing chamber for processing a substrate, a load lock chamber, a gas supply line for supplying gas into the load lock chamber, exhaust lines for exhausting the load lock chamber, a moving mechanism provided in the load lock chamber and capable of moving the substrate, local exhaust lines capable of locally exhausting dust generating portions of the moving mechanism, a flow rate controlling device provided in the gas supply line and flow rate controlling devices provided in the local exhaust lines. The flow rates of the flow rate controlling devices are monitored and controlled to control the inside pressure of the load lock chamber to be slightly higher than the atmosphere pressure, thereby preventing the backward flow from the vent line.